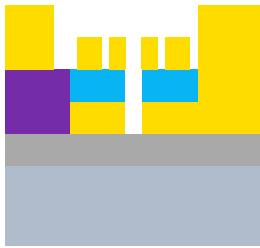1. Electrode Exposure

2. Active Area Etch

3. SiO2 Backfill

4. 3x Metal Deposition

5. Release Window Etch

6. XeF2 Release

aSi	Al_2O_3
Metal	SiO_2
LN	